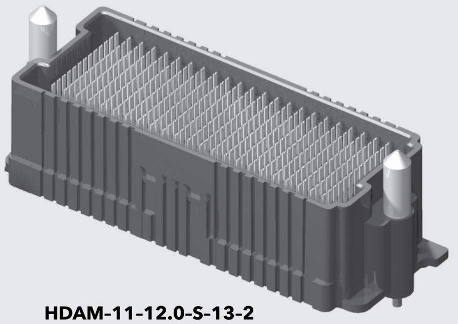
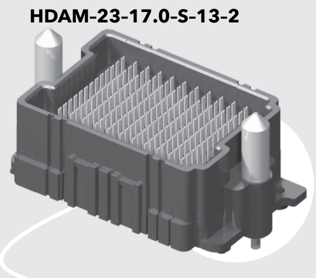

HDAM-11-12.0-S-13-2


HDAM-23-17.0-S-13-2

(2.00 mm) .0787"

HDAM SERIES

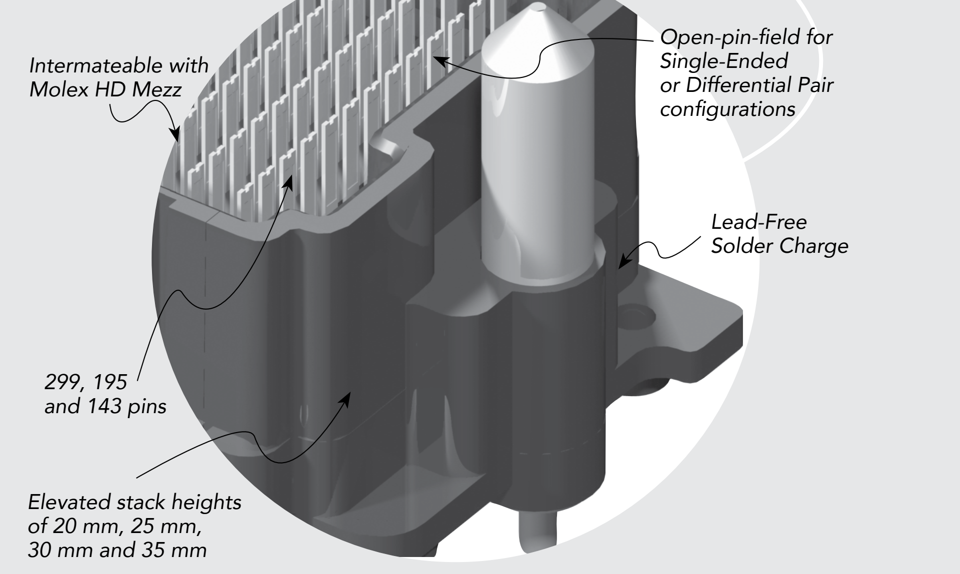
RUGGED ELEVATED HIGH-DENSITY ARRAY

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
1.8 A per pin
(6 adjacent pins powered)
Working Voltage:
230 VAC/325 VDC
Mated Cycles:
100
RoHS Compliant:
Yes
Lead-Free Solderable:
Yes

Mates with:
HDAF

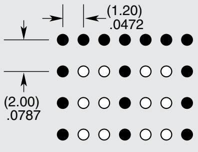


RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

ALSO AVAILABLE
Contact Samtec

- Tin-Lead Solder Charge
- Other platings

Notes:
HD Mezz is a trademark of Molex Incorporated

Some lengths, styles and options are non-standard, non-returnable.

HDAM – NO. PINS PER ROW – LEAD STYLE – PLATING OPTION – 13 – SOLDER TYPE – OPTION – PACKAGING

NO. PINS PER ROW
–11, –15, –23

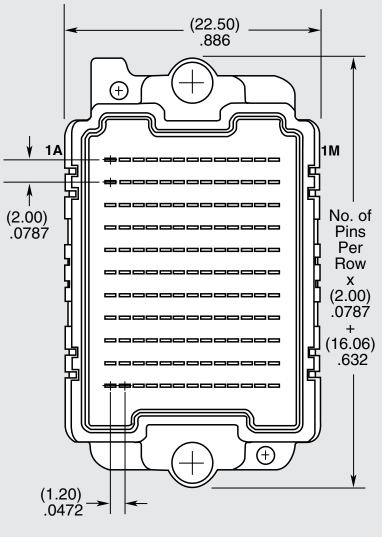
LEAD STYLE
Specify LEAD STYLE from chart

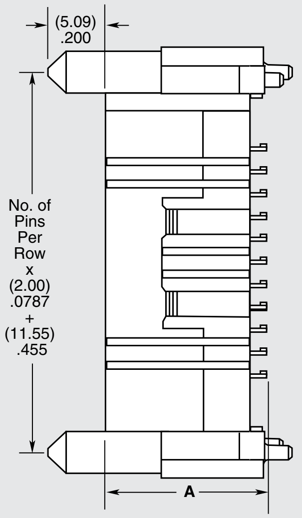
PLATING OPTION
–S
= 30 µ" (0.76 µm) Gold on contact area, Matte Tin on tails and guide pins

SOLDER TYPE
–2
= Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge

OPTION
–P
= Pick & Place Pad

PACKAGING
Leave blank for tray packaging
–TR
=Tape & Reel
–FR
= Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)





LEAD STYLE	A
–12.0	(14.41) .567
–17.0	(19.41) .764